

Title (en)

METHOD AND ARRANGEMENT FOR MEASURING THE NIP PRESSURE AND/OR PRESSURE PROFILE IN THE NIP OF A PRINTING UNIT OF A PRINTING PRESS

Title (de)

VERFAHREN UND ANORDNUNG ZUR MESSUNG DES ANPRESSDRUCKS UND/ODER DES DRUCKPROFILS BEIM WALZENFLÄCHENABSTAND EINER DRUCKEINHEIT EINER DRUCKMASCHINE

Title (fr)

PROCÉDÉ ET DISPOSITIF POUR MESURER LA PRESSION DANS LA PINCE ET/OU LE PROFIL DE PRESSION DANS LA PINCE D'UNE UNITÉ D'IMPRESSION D'UNE PRESSE À IMPRIMER

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Application

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Abstract (en)

[origin: WO2009101251A2] The invention relates to a method and an arrangement for measuring the nip pressure and/or pressure profile in the nip of a printing unit of a printing press. A force and/or pressure sensor, such as a pressure sensitive film, for example, an EMFi film sensor, is installed on the counter roller, rubber roller or roller forming the nip of a printing unit which participates in the printing unit in transferring printing ink onto the paper, plastic or other thin sheet-like material surface, wherein the pressure sensitive film is adapted to produce, in connection with a deformation of the force and/or pressure sensor, an electrical signal corresponding to the magnitude of the deformation. The rollers forming the nip are caused to rotate in relation to one another such that the nip pressure of the nip causes a deformation of the force and/or pressure sensor producing an electrical signal corresponding to the deformation of the nip. The nip pressure and/or pressure profile of the nip is calculated by using the electrical signal produced by the deformation of the force and/or pressure sensor.

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